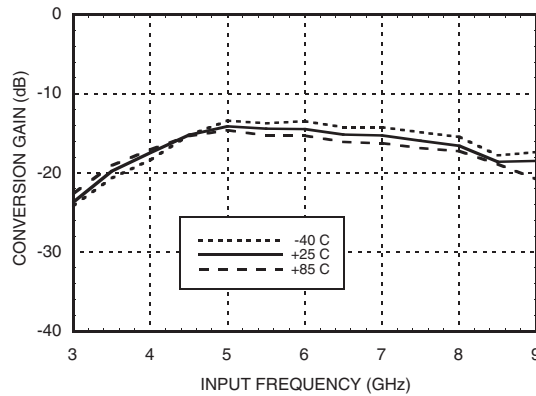


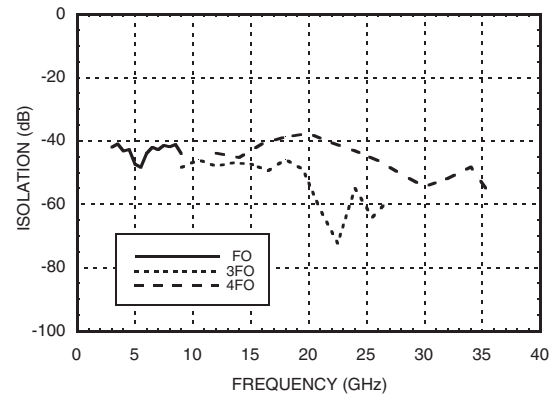


**GaAs MMIC SMT PASSIVE FREQUENCY
DOUBLER, 4 - 8 GHz INPUT**

**Conversion Gain vs. Temperature
@ +15 dBm Drive Level**

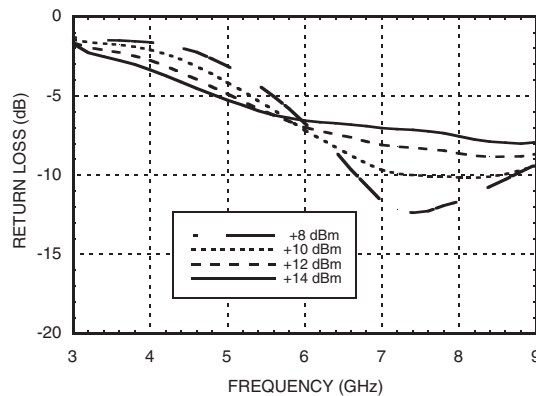


Isolation @ +15 dBm Drive Level*

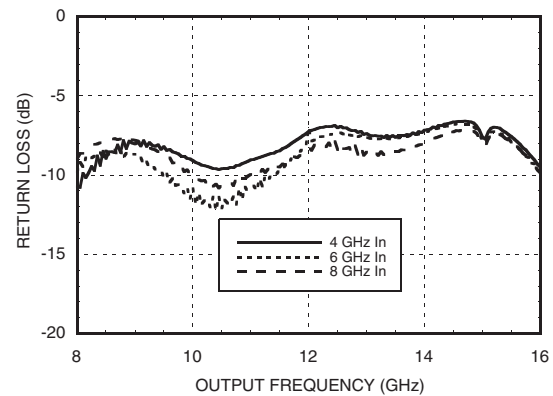


*With respect to input level

Input Return Loss vs. Drive Level



**Output Return Loss for
Several Input Frequencies**



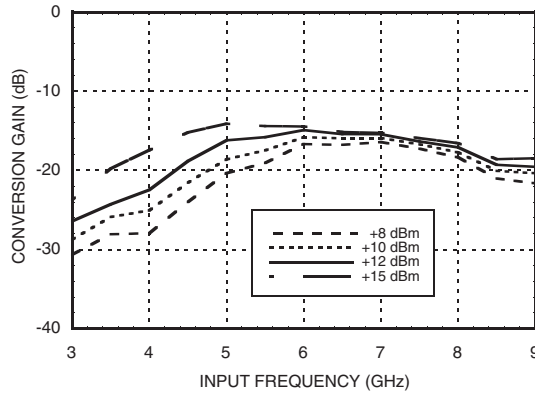


**GaAs MMIC SMT PASSIVE FREQUENCY
DOUBLER, 4 - 8 GHz INPUT**

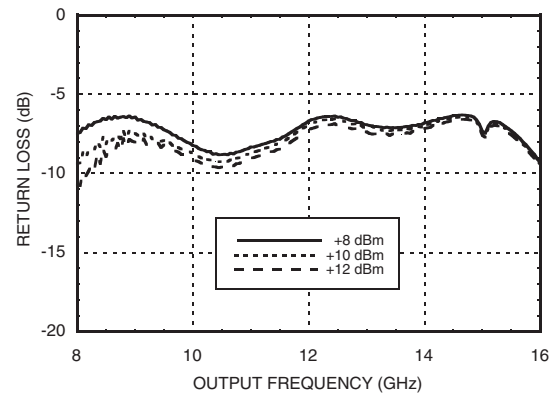
7

FREQ. MULTIPLIERS - PASSIVE - SMT

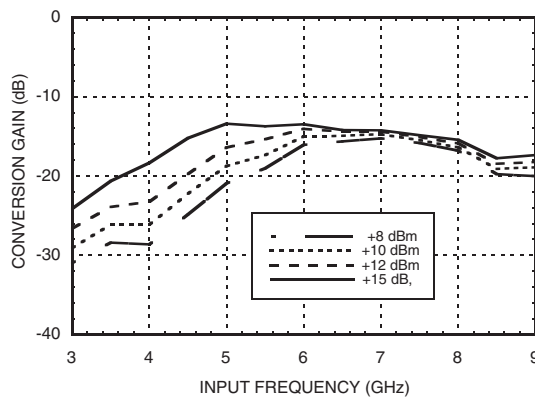
Conversion Gain @ 25 °C vs. Drive Level



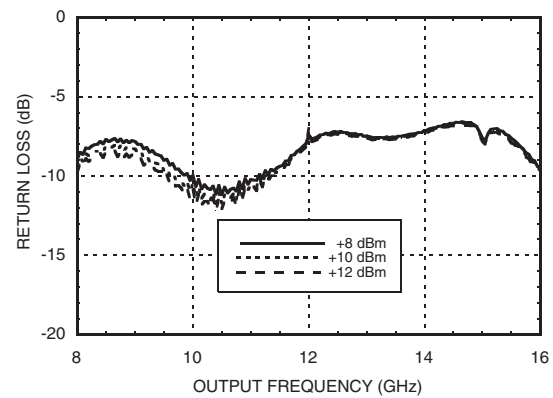
Output Return Loss with 4 GHz Input



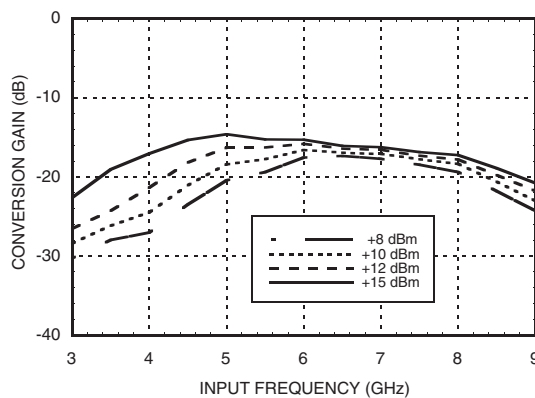
Conversion Gain @ -40 °C vs. Drive Level



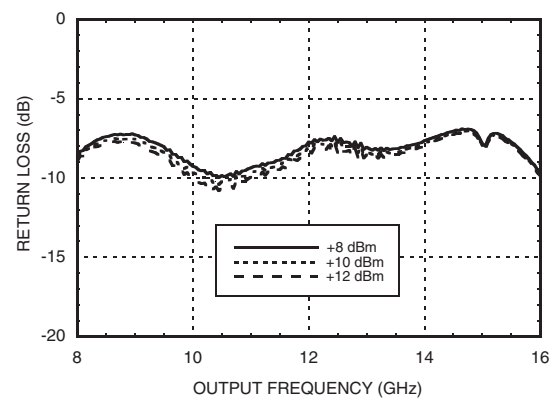
Output Return Loss with 6 GHz Input



Conversion Gain @ +85 °C vs. Drive Level



Output Return Loss with 8 GHz Input



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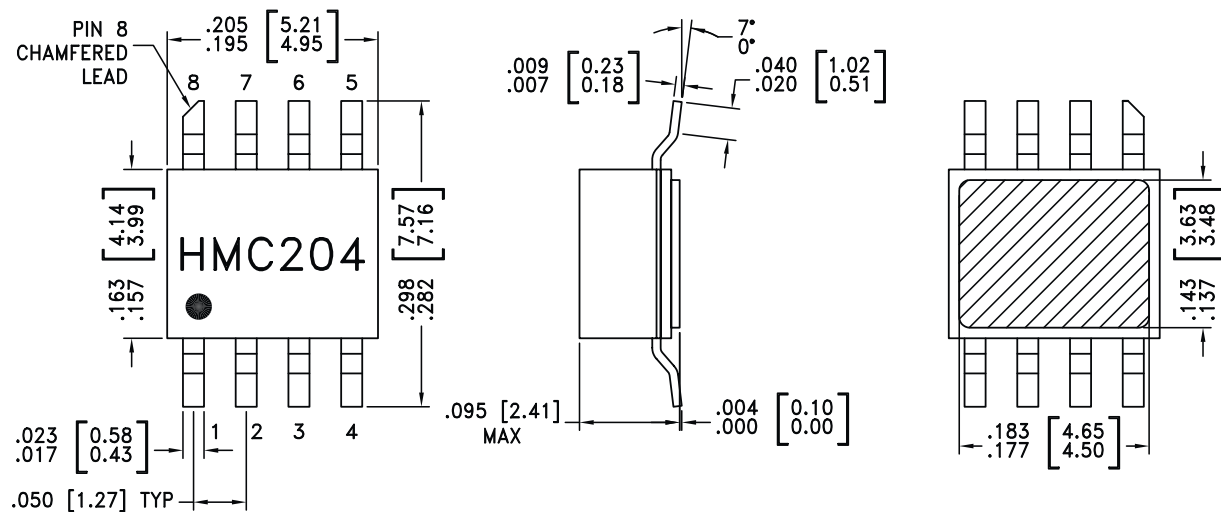
**GaAs MMIC SMT PASSIVE FREQUENCY
DOUBLER, 4 - 8 GHz INPUT**

Absolute Maximum Ratings

Input Drive	+27 dBm
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

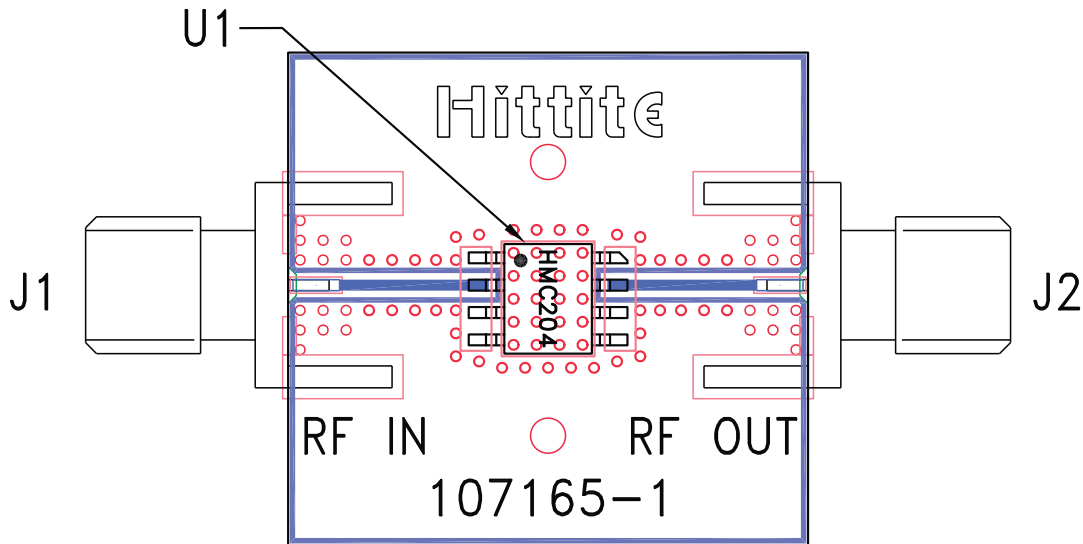
Outline Drawing

NOTES:

1. PACKAGE BODY MATERIAL: WHITE ALUMINA 92%
2. LEAD, PACKAGE BOTTOM MATERIAL: COPPER
3. PLATING: ELECTROLYTIC GOLD 100 - 200 MICROINCHES OVER ELECTROLYTIC NICKEL 100 TO 200 MICROINCHES.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
5. PACKAGE LENGTH AND WIDTH DIMENSIONS DO NOT INCLUDE LID SEAL PROTRUSION .005 PER SIDE.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB PF GROUND.

**GaAs MMIC SMT PASSIVE FREQUENCY
DOUBLER, 4 - 8 GHz INPUT**



Evaluation PCB



List of Materials for Evaluation PCB 107196 ^[1]

Item	Description
J1, J2	PCB Mount SMA Connector
U1	HMC204C8, Doubler
PCB [2]	107165 Eval Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should be generated with proper RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. The evaluation circuit board shown is available from Hittite upon request.

**GaAs MMIC SMT PASSIVE FREQUENCY
DOUBLER, 4 - 8 GHz INPUT****Notes:**